

AMENDMENTS

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) A lead-free solder consisting essentially of:
 - (a) 1.0 to ~~3.49~~ 2.99 wt.% of Ag;
 - (b) 0.4 to ~~0.99~~ 1.3 wt.% of Cu;
 - (c) 0.02 to 0.06 wt.% of Ni;
 - (d) 0.02 to 0.06 wt.% of Fe; and
 - (e) a balance of Sn;wherein said Ni serves to lower ~~a~~ the copper dissolution rate of said solder.
2. (Currently amended) The solder according to claim 1, wherein ~~a~~ the content of Ni is in a range from 0.02 to 0.04 wt.%.
3. (Previously presented) The solder according to claim 1, wherein said solder has a copper dissolution rate of 0.20 μ m or less.
4. (Previously presented) The solder according to claim 1, wherein said solder has a liquidus temperature of 240°C or lower.
5. (Previously presented) The solder according to claim 1, wherein said solder has a liquidus temperature of 230°C or lower.
6. (Original) The solder according to claim 1, wherein said solder has a viscosity of 2.5 cP or lower.
7. (Previously cancelled)
8. (Original) The solder according to claim 1, further containing 0.02 to 0.05 wt.% of Fe.
9. (Currently amended) A lead-free solder consisting essentially of:

- (a) 1.0 to ~~3.49~~ 2.99 wt.% of Ag;
- (b) 0.4 to ~~0.99~~ 1.3 wt.% of Cu;
- (c) 0.02 to 0.06 wt.% of Fe; and
- (d) a balance of Sn;

wherein said Fe serves to lower ~~a~~the copper distribution rate of said solder.

10. (Currently amended) The solder according to claim 9, wherein ~~a~~the content of Fe is in ~~a~~the range from 0.02 to 0.05 wt.%.

11. (Previously presented) The solder according to claim 9, wherein said solder has a copper dissolution rate of 0.20 μm or less.

12. (Previously presented) The solder according to claim 9, wherein said solder has a liquidus temperature of 240°C or lower.

13. (Previously presented) The solder according to claim 9, wherein said solder has a liquidus temperature of 230°C or lower.

14. (Original) The solder according to claim 9, wherein said solder has a viscosity of 2.5 cP or lower.

Claims 15-20 (cancelled).

21. (New) A lead-free solder consisting essentially of:

- (a) 1.0 to 3.49 wt.% of Ag;
- (b) 0.4 to 0.99 wt.% of Cu;
- (c) 0.02 to 0.06 wt.% of Ni;
- (d) 0.02 to 0.06 wt.% of Fe; and
- (e) a balance of Sn;

wherein said Ni serves to lower the copper dissolution rate of said solder.

22. (New) A lead-free solder consisting essentially of:

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- (a) 1.0 to 3.49 wt.% of Ag;
- (b) 0.4 to 0.99 wt.% of Cu;
- (c) 0.02 to 0.06 wt.% of Fe; and
- (d) a balance of Sn;

wherein said Fe serves to lower the copper dissolution rate of said solder.

23. (New) The solder according to claim 1, wherein the content of Cu is in the range of from 0.4 to 0.99 wt.%.

24. (New) The solder according to claim 9, wherein the content of Cu is in the range of from 0.4 to 0.99 wt.%